

Commissioner of Patents & Trademarks

07-03-2008

Washington, D.C. 20231

Form PTO-1595

(Rev. 03/01)



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U.S. DEPARTMENT OF COMMERCE

U.S. PATENT AND TRADEMARK OFFICE

To the honorable Commissioner o

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ched original document or copy thereof:

6-24-08

1. Name of Conveying Party(ies):

LIM, Fong
LEE, See Yau
HENG, Yang Hong

2. Name and Address of Receiving Party(ies):

Name: Infineon Technologies Austria AG
Street Address: Siemensstrasse
Street Address:
City: Villach
State/Country: Republic of Austria Postal Code: 9500

Additional name(s) of conveying party(ies) attached? Yes No

Additional name(s) and addresses attached? Yes No

3. Nature of Conveyance:

- Assignment Change of Name
- Security Agreement Other:
- Merger

Execution Date: 05302008

4. Application Number(s) or Patent Number(s):

- Assignment is being filed together with new application and the first execution date of application is : 05302008
- Application has been filed already and the application filing date is:

A. Patent Application Number(s):

B. Issued Patent Number(s):

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning this matter should be mailed:

CUSTOMER NUMBER 00136 -or-
JACOBSON HOLMAN PLLC
400 Seventh Street, N.W.
Washington, D.C. 20004-2218
Tel. 202-638-6666

Attorney Docket Number: P72682US0

6. Total number of applica-
tions and patents involved: 1

7. Total Fee (37 CFR 3.41): \$ 40.00

- Enclosed
- Any deficiencies in enclosed fees are authorized to be charged to Deposit Account No. 06-1358.

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8. Statement and Signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Allen S. Melser 27,215

June 24, 2008

Name of Person Signing, Reg. No.

Signature

Date

Total number of pages including cover sheet, attachments, and documents:

6

U.S. Patent Appl. No.
Filing Date

Docket No.

PATENT ASSIGNMENT**PARTIES TO THE ASSIGNMENT**

Assignor: Fong Lin

Assignor: See Yuen Lee

Assignor: Yang Hong Heng

Assignee:
Infineon Technologies Austria AG
Siemensstrasse 1
9500 Villach
Republic of Austria

AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled
"Semiconductor Chip Assembly" for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this

Assignment on the same day as he/she signs the Declaration and Power of

Attorney);

U.S. Patent Appl. No.

Docket No.

Filing Date June 24, 2008

WHEREAS ASSIGNEE (listed above), a corporation of the Republic of Austria is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

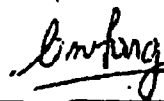
U.S. Patent Appl. No.

Docket No.

Filing Date

30/5/2008

Date



Name

1st Inventor Fong Lim

Jan 2008

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Attachment 15c

U.S. Patent Appln. No.
Filing Date

Docket No.

2015/24/08
Date


Name 2nd Inventor See Yau Lee

Jan 2008

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